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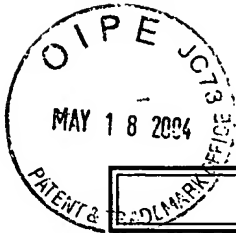
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Electronic Patent Application Submission
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Application ID: 10774893
Title of Invention: LEADFRAME FOR
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First Named Inventor: HYUNG LEE
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Title of Invention	LEADFRAME FOR SEMICONDUCTOR PACKAGE									
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<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids1-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids1-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
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	us-ids.dtd									
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Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
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	2	20010014538	2001-08-16	KWAN ET AL.			
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	9	20030030131	2003-02-13	LEE ET AL.			
	10	20030073265	2003-04-17	HU ET AL.			

Signature

Examiner Name	Date